

8/7/6/5/4/3/2/1-Phase Synchronous-Rectified Buck Controller with SMBus Digital Interface

General Description

The uP9512R is an 8/7/6/5/4/3/2/1-phase PWM controller specifically designed to provide high-precision output voltage system for next generation GPUs. The uP9512R provides programmable output voltage and active voltage positioning functions to adjust the output voltage as a function of the load current, so it is optimally positioned for a load current transient.

The uP9512R supports NVIDIA Open Voltage Regulator type 4i+ with PWMVID feature. The PWMVID input is buffered and filtered to generate accurate reference voltage and the output voltage is precisely regulated to the reference input. The integrated SMBus interface provides user the flexibility to optimize the performance and efficiency.

The uP9512R uses per-channel inductor DCR current sensing for channel current balance and channel current limit. The continuous total DCR current sensing is used for load line programming and total output current protection. The uP9512R also provides hardware setting to adjust the operating phase number in different load current state.

Other features include adjustable soft-start, under voltage protection, over voltage protection and power good output. The uP9512R is available in a VQFN5x5-40L package.

Ordering Information

| Order Number | Package | Top Marking |
|--------------|---------------|-------------|
| uP9512RQGJ | VQFN5x5 - 40L | uP9512R |

Note:

- (1) Please check the sample/production availability with uPI representatives.
- (2) uPI products are compatible with the current IPC/ JEDEC J-STD-020 requirements. They are halogen-free, RoHS compliant and 100% matte tin (Sn) plating that are suitable for use in SnPb or Pb-free soldering processes.

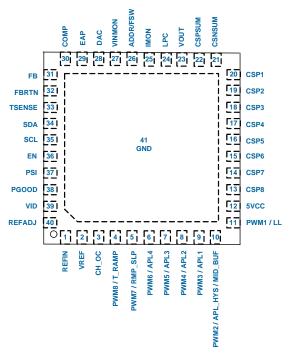
Applications

Middle-High End GPU Core Power Supplies

Features

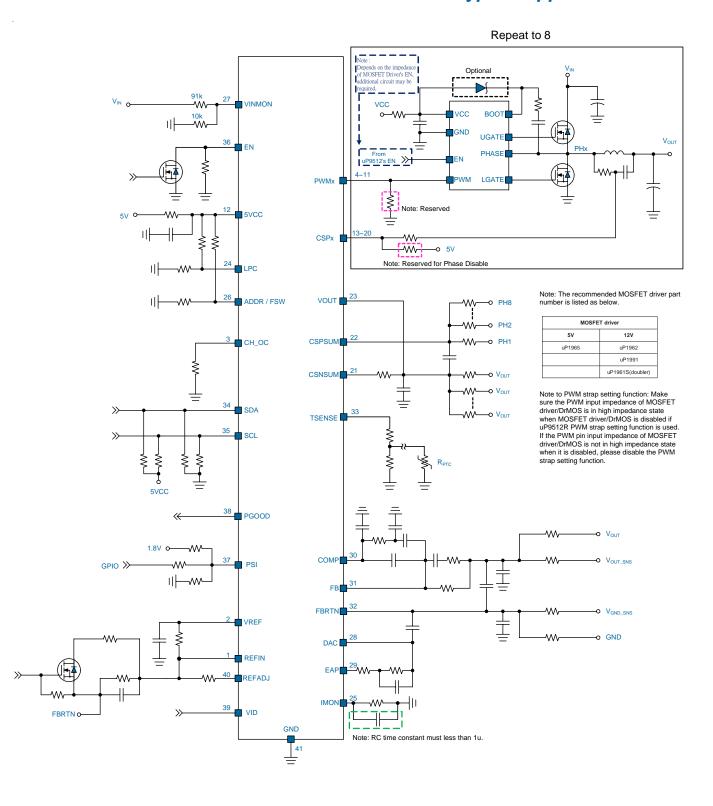
- Support NVIDIA's Open VReg Type 4i+ PWMVID Technology
- SMBus Interface for Performance and Efficiency Optimization
 - Dynamic Programmable VR Parameters
 - Programmable Protection Thresholds
 - VR Output Reporting
- Selectable 8/7/6/5/4/3/2/1-Phase Operation by Hardware Setting
- Support up to 2MHz Operation Frequency
- □ Continuous Inductor DCR Current Sensing
- Auto-Phase Shedding
- Adjustable Soft-Start Time
- Power State Input (PSI)
- Power Good Indication
- Channel Current Limit Protection
- Total Output Over Current Protection
- Over/Under Voltage Protection
- Over Temperature Protection
- RoHS Compliant and Halogen Free

Pin Configuration





Typical Application Circuit





| No. | Name | Pin Function |
|-----|--------------------------|--|
| 1 | REFIN | Reference Input. Connect this pin to an external reference voltage through a resistor or connect to the output of the REFADJ circuit. |
| 2 | VREF | Reference Voltage. 2V LDO voltage output pin. Connect an at least 1 uF decoupling capacitor between this pin and GND. |
| 3 | CH_OC | Channel Current Limit. Connect a resistor from this pin to GND to set the per- channel current limit threshold. |
| 4 | PWM8/T_RAMP | Phase 8 PWM Output and Soft-Start Time. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the soft-start time. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to set the soft-start time. The resistor value should be greater than $15k\Omega$. |
| 5 | PWM7/RMP_SLP | Phase 7 PWM Output and RAMP Slope. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the slope of internal RAMP signal. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the RAMP slope. The resistor value should be greater than $15k\Omega$. |
| 6 | PWM6/APL4 | Phase 6 PWM Output and Auto-Phase Shedding Threshold 4. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 4. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 4. The resistor value should be greater than $15k\Omega$. |
| 7 | PWM5/APL3 | Phase 5 PWM Output and Auto-Phase Shedding Threshold 3. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 3. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 3. The resistor value should be greater than $15k\Omega$. |
| 8 | PWM4/APL2 | Phase 4 PWM Output and Auto-Phase Shedding Threshold 2. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 2.Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 2. The resistor value should be greater than $15k\Omega$. |
| 9 | PWM3/APL1 | Phase 3 PWM Output and Auto-Phase Shedding Threshold 1. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 1.Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 1. The resistor value should be greater than $15k\Omega$. |
| 10 | PWM2/APL_HYS/ MID_BUF | Phase 2 PWM Output, Hysteresis of Auto-Phase Shedding and PWM Middle State Mode Control. It outputs a PWM logic signal for external MOSFET driver and it is also used to set the hysteresis of auto-phase shedding and PWM middle state mode selection. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the hysteresis of auto-phase shedding and selects the PWM middle state mode. The resistor value should be greater than $15k\Omega$. |
| 11 | PWM1/LL | Phase 1 PWM Output and Load Line. It outputs a PWM logic signal for external MOSFET driver and it is also used to program the DC load line enable threshold. Connect a resistor from this pin to GND to set the DC load line enable threshold. The resistor value should be greater than $15k\Omega$. |



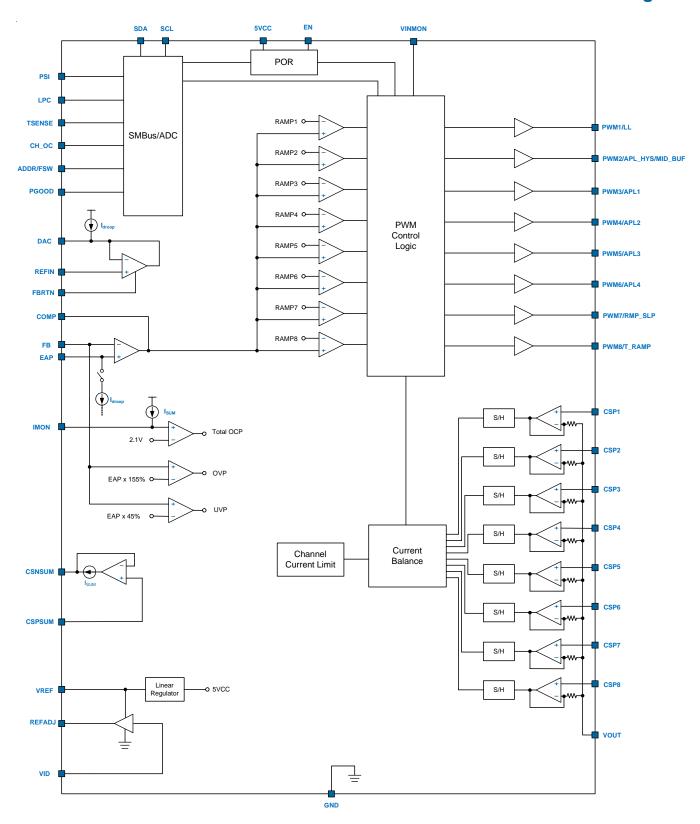
| No. | Name | Pin Function |
|-----|----------|--|
| 12 | 5VCC | Supply Input for the IC. Connect this pin to a 5V voltage source with RC filter. Connect this pin to a 5V supply and decouple with a ceramic capacitor of 1uF minimum. |
| 13 | CSP8 | Non-Inverting Input of Current Sensing Amplifier for Phase 8. This pin is used for differentially sensing phase 8 output current. Connect this pin to the node between the RC current sense elements. |
| 14 | CSP7 | Non-Inverting Input of Current Sensing Amplifier for Phase 7. This pin is used for differentially sensing phase 7 output current. Connect this pin to the node between the RC current sense elements. |
| 15 | CSP6 | Non-Inverting Input of Current Sensing Amplifier for Phase 6. This pin is used for differentially sensing phase 6 output current. Connect this pin to the node between the RC current sense elements. |
| 16 | CSP5 | Non-Inverting Input of Current Sensing Amplifier for Phase 5. This pin is used for differentially sensing phase 5 output current. Connect this pin to the node between the RC current sense elements. |
| 17 | CSP4 | Non-Inverting Input of Current Sensing Amplifier for Phase 4. This pin is used for differentially sensing phase 4 output current. Connect this pin to the node between the RC current sense elements. |
| 18 | CSP3 | Non-Inverting Input of Current Sensing Amplifier for Phase 3. This pin is used for differentially sensing phase 3 output current. Connect this pin to the node between the RC current sense elements. |
| 19 | CSP2 | Non-Inverting Input of Current Sensing Amplifier for Phase 2. This pin is used for differentially sensing phase 2 output current. Connect this pin to the node between the RC current sense elements. |
| 20 | CSP1 | Non-Inverting Input of Current Sensing Amplifier for Phase 1. This pin is used for differentially sensing phase 1 output current. Connect this pin to the node between the RC current sense elements. |
| 21 | CSNSUM | Inverting Input of Total Current Sense Amplifier. |
| 22 | CSPSUM | Non-Inverting Input of Total Current Sense Amplifier. |
| 23 | VOUT | Output Voltage. Inverting input of current sensing amplifier for phase1~phase8. Connect this pin directly to output voltage plane. |
| 24 | LPC | Low Phase Count. Connect a voltage divider from 5VCC to this pin to set the operation phase number of Warm Boot and Cold Boot. Do NOT connect any decoupling capacitor to this pin. |
| 25 | IMON | Output Current Monitor. The output current of this pin is proportional to the total load current. The total load current is sensed and flows out of this pin, and a resistor from this pin to GND makes the IMON voltage proportional to the total output current. The IMON voltage is monitored for total output over current protection. A capacitor can be connected from IMON to GND to adjust the response time of IMON. Care must be taken when adding capacitor to IMON. The RC time constant of R_{IMON} and C_{IMON} should be less than 1u. |
| 26 | ADDR/FSW | SMBus Device Address and Operation Frequency. Connect a voltage divider from 5VCC to this pin to select the SMBus device address and operation frequency. Do NOT connect any decoupling capacitor to this pin. |



| No. | Name | Pin Function |
|-------|-------------|---|
| 27 | VINMON | Power Stage Input Voltage Monitor. Connect this pin to the power stage input VIN with a voltage divider. The controller senses the voltage on this pin for power stage input voltage VIN detection. It is recommended to use resistor divider with 1/10 dividing ratio from VIN. For example, use $91k\Omega/10k\Omega$ resistor divider is a good practice. |
| 28 | DAC | DAC Output. The output voltage of this pin is the reference votlage. |
| 29 | EAP | Non-Inverting Input of the Error Amplifier . Connect a resistor between this pin and DAC pin to set the droop (load line) function. |
| 30 | COMP | Output of Control Loop Error Amplifier. |
| 31 | FB | Inverting Input of the Error Amplifier. |
| 32 | FBRTN | Output Voltage Feedback Return. Inverting input to the differential voltage sense amplifier. FBRTN is the reference point in DAC output voltage measurement.Connect this pin directly to the GPU output voltage feedback return sense point. |
| 33 | TSENSE | Thermal Monitoring Input. Connect a specified positive temperature coefficient (PTC) thermistor network from this pin to GND for VR temperature sensing. |
| 34 | SDA | SMBus Data Input. This pin is input or output of serial bus data signal. If the SMBus is not available, this pin can be a hardware setting pin for single phase operation mode selection. Find the detail description in "SMBus (SCL & SDA)" section. |
| 35 | SCL | SMBus Clock Input. This pin receives serial bus clock signal input. If the SMBus is not available, this pin can be a hardware setting pin for single phase operation mode selection. Find the detail description in "SMBus (SCL & SDA)" section. |
| 36 EN | | Enable. Connect a $10k\Omega$ resistor from this pin to ground to enable the PWM strap function and place this resistor close to the controller. To disable PWM strap function, use $24k\Omega$ instead. Do NOT use resistance values other than the value specified here. Do NOT connect any capacitor directly to this pin. Refer to the typical application circuit, it is recommended to use a MOSFET with its drain connected to EN pin without a pull-up resistor for power sequence control. Do NOT connect EN pin directly to a voltage source for sequence control. |
| 37 | PSI | Power Saving Input. An input pin receiving power saving control signal from GPU. |
| 38 | PGOOD | Power Good Indication. Connect this pin to a voltage source with a pull-up resistor. |
| 39 | VID | VID. PWMVID input pin. |
| 40 | REFADJ | Reference Adjustment. PWMVID output pin. Connect this pin with an RC integrator to generate REFIN voltage. |
| | Exposed Pad | Ground. The exposed pad is the ground of logic control circuits, it must be soldered to a large PCB and connected to GND. |



Functional Block Diagram





Power On Reset (POR)

Figure 1 shows the power ready detection circuit. The 5VCC voltage is monitored for power on reset with typically 4.3V threshold at its rising edge. When 5VCC is ready, the controller waits for EN to start up. When EN pin is driven above 0.2V, the controller begins its start up sequence. When EN pin is driven below 0.1V, the controller will be turned off, and it will clear all fault states to prepare to next soft-start once the controller is re-enabled.

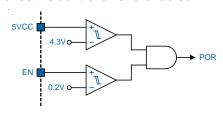


Figure 1. Circuit of Power Ready Detection

Power Input Monitor

VINMON is the power stage input voltage sense pin. Connect this pin to power stage input voltage (VIN) with a voltage divider and always keep VINMON as 1/10 of power stage input voltage. When VINMON less than typically 0.2V at POR, the uP9512R will force start up at single phase and disables the cold boot, warm boot, PSI and autophase function. Once this condition is triggered, it can only be reset by re-POR or EN restart.

Enable Control

The EN pin controls the enable and disable of this device. The resistor R_{FN} connected between EN pin to ground is used to implement this function. It is recommended to use a small MOSFET with its drain connected to EN pin without pull up resistor for power sequence control as shown in Figure 2. Precaution should be taken while implementing the power sequence circuit to EN pin. Do NOT use other resistance value other than values specified in the PWM Strap section and do NOT connect EN pin directly to a voltage source. Do NOT connect EN pin directly to any sequencing circuit of the system. Make sure the slew rate of the gate signal (EN#) of Q1 is fast and not affected by any additional circuit. When $V_{FN} < 0.1V$ and sustain 2us, the UVLO(Under Voltage Lock Out) event is triggered. Then, controller shuts down and reset all the hardware setting parameters.

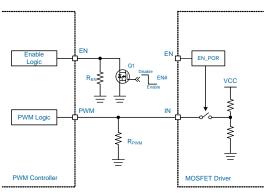


Figure 2. Enable Sequence Control

PWM Strap Function

The uP9512R implements PWM strap function to provide more functional programming in a limited pin out. The PWM strap function can be controlled by the $R_{\scriptscriptstyle EN}$ resistor connected from EN pin to GND. Use $R_{\scriptscriptstyle EN}$ =10k Ω to activate the PWM strap function and use $R_{\scriptscriptstyle EN}$ =24k Ω for function disable. To ensure correct PWM strap function setting. The input impedance of PWM pin of companion MOSFET driver should be in high-impedance state during the initial setting period prior to soft-start (Figure 2). Otherwise all the function setting by PWM pins can only be done via SMBus interface.

Soft Start and Power Up Sequence

The uP9512R features a programmable soft start function to limit the surge current from power supply input. Controller starts the soft-start process right on $\rm V_{EN}>0.2V$ with typical 550us initialization time ($\rm T_{INIT}$). The output voltage ramp up time ($\rm T_{RAMP}$) during soft start period is determined by the resistor $\rm R_{PWM8}$ connected from PWM8 pin to GND. Table1 shows the $\rm T_{RAMP}$ time and recommended $\rm R_{PWM8}$ resistance.

Table 1. T_{RAMP} Time and Recommended R_{PWM8}

| R _{PWM8} | T _{RAMP} |
|-------------------|-------------------|
| 39kΩ | 160us |
| 100kΩ | 320us |
| 150kΩ | 1.28ms |
| unstuffed | 640us |

If R_{PWM8} resistor is unstuffed, the output voltage ramp up time during soft-start period is typical 640us. If there is no fault detected at the end of soft-start, the controller then asserts PGOOD when the output voltage reaches its target without delay. Figure 3 shows the power up sequence of the uP9512R.

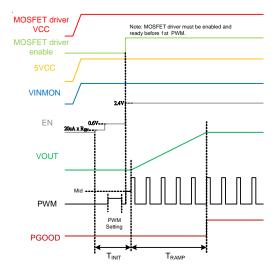


Figure 3 Power Up Sequence



PWMVID Function

The PWMVID signal from GPU is applied to the VID pin, which is the input pin of the internal buffer. This buffer plays the role of level shifting, and the output of this buffer is injected into the external RC integrator to generate REFIN voltage, which can be calculated as:

$$V_{REFIN} =$$

$$V_{VREF} \times D \times \frac{R2/(R3 + R4 + R5)}{R1 + R2/(R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5} +$$

$$V_{VREF} \times \frac{R1//(R3 + R4 + R5)}{R2 + R1//(R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5}$$

where V_{REFIN} is the DC voltage of REFIN, V_{VREF} is the voltage of VREF (typically 2V), and D is the duty cycle of PWMVID input. The VREF pin is an internal LDO, therefore an output decoupling capacitor is required. Recommend connecting at least a 1uF capacitor from VREF pin to local GND.

Boot Mode and Standby Mode

The PWMVID structure includes two operation modes: boot mode and standby mode. During boot mode, controller ignores the PWMVID signal before PGOOD signal goes high and the REFADJ pin enters high impedance state. The REFIN voltage during boot mode can be calculated as:

$$V_{REFIN,BOOT} = V_{VREF} \times \frac{R4 + R5}{R2 + R3 + R4 + R5}$$

During standby mode, other than GPU stopping the PWMVID transaction, an external system standby signal additionally controls the entry of standby mode. An additional external switch should be connected in parallel with the original PWMVID resistors as shown in Figure 4 to generate the standby mode voltage:

 $V_{REFIN,STDBY} =$

$$V_{VREF} \times \frac{(R3 + R4 + R5)//R_{STDBY}}{R2 + (R3 + R4 + R5)//R_{STDBY}} \times \frac{R4 + R5}{R3 + R4 + R5}$$

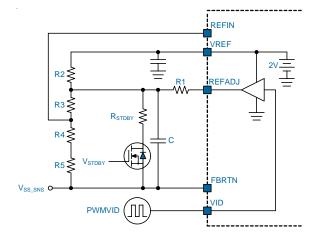


Figure 4. PWMVID Structure

Channel Current Balance

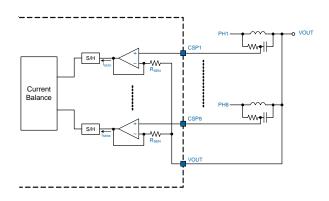


Figure 5. Current Balance Circuit

The uP9512R senses each phase current through CSPx pin for current balancing. The phase current signal is sampled and held when the low-side MOSFETs are turned on. The sensed current I_{SENx} can be determined by the following equation:

$$I_{SENx} = \frac{\Delta V_{CSPx}}{R_{SEN}}$$

Where I $_{\text{SENx}}$ is the sampled and held phase current signal, ΔV_{CSPx} is the differential voltage between CSPx and VOUT and the R $_{\text{SEN}}$ is internal sense resistor which is typical 655 Ω . The sensed current I $_{\text{SENx}}$ is mirrored to the current balance circuit, comparing between each other, and generating current adjusting signals for each phase. The current balance circuit increases the duty cycle of the phase whose phase current is smaller than others and decrease the duty cycle of the phase whose phase current is larger than others.

Total Load Current Sense

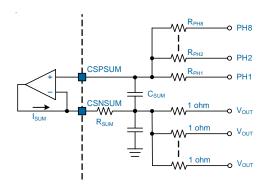


Figure 6. Total Load Current Sense

The uP9512R uses a low input offset current sense amplifier (CSA) to sense the total load current flowing through inductors for droop function by CSPSUM and CSNSUM as shown in Figure 6.



The voltage across C_{SUM} is proportional to the total load current, and the output current of $\text{CSA}(I_{\text{SUM}})$ is also proportional to the total load current of the voltage regulator. The sensed current I_{SUM} represents the total output current of the regulator, and it is directly used for droop function, total output over current protection and auto-phase shedding function. I_{SUM} is calculated as follows.

$$I_{SUM} = \frac{I_{OUT} \times \frac{R_{DC}}{N}}{R_{SUM}}$$

In this inductor current sensing topology, $R_{\rm PH}$ and $C_{\rm SUM}$ must be selected according to the equation below:

$$k \times \frac{L}{R_{DC}} = \frac{R_{PH} \times C_{SUM}}{N}$$

where R_{DC} is the DCR of the output inductor L, N is the operation phase number. Theoretically, k should be equal to 1 to sense the instantaneous total load current. But in real application, k is usually between 1.2 to 1.8 for better load transient response. Note that the resistance value of R_{SUM} must be less than $2k\Omega$ to ensure the current sensing circuit in normal operation.

DC Load Line

The uP9512R implements DC load line with programmable enable threshold for user to optimize load transient performance. When DC load line is activated, the DC output voltage decreases as the output DC current increases. The enable threshold of DC load line is set by a $R_{\tiny PWM1}$ resistor connected from PWM1 pin to GND. An $I_{\tiny LLTH}$ current is generated by a 2V voltage source and $R_{\tiny PWM1}$ during $T_{\tiny INIT}$ time, it is calculated as :

$$I_{LLTH} = \frac{2V}{R_{PWM1}}$$

If the I_{SUM} current is greater than I_{LLTH} current, controller then activates the DC load line function. The I_{LLTH} current must in the range of 10uA to 80uA (R_{PWM1}=200k Ω to 25k Ω), out of the specified range should be avoided.

AC Load Line

The AC load line function is used to improve the load transient reponse. This function only takes effect in the load transient condition when the output voltage has instantaneous change due to transient load current. It does not affect the output DC voltage when the load current is in DC condition. Connect a $16k\Omega$ resistor (or resistance range from $15k\Omega$ to $18k\Omega$) from PWM1 to GND to enable the AC load line function. The response time of AC load line is typically 80us, and the voltage droop is generated by the $R_{\mbox{\tiny DROOP}}$ resistor (see "Voltage Control Loop" section for details). The AC load line function & the response time can also be programmed via SMBus interface.

Voltage Control Loop

Figure 7 illustrates the voltage control loop of the uP9512R.

FB and EAP are negative and positive inputs of the error amplifier respectively. The error amplifier modulates the COMP voltage (V_{COMP}) and the duty cycle of regulator to force V_{FB} follows V_{EAP} . The I_{DROOP} current is mirrored to the EAP pin and creates a voltage at EAP pin as:

$$V_{EAP} = V_{DAC} - I_{DROOP} \times R_{DROOP}$$

$$I_{\it DROOP} = I_{\it SUM} - I_{\it LLTH}$$
 (if DC load line is activated)

$$I_{DROOP} = I_{SUM}$$
 (if AC load line is activated)

Where V_{DAC} is output of V_{REFIN} , R_{DROOP} is an external resistor connected between DAC and EAP pins for adjusting load line slope and I_{DROOP} is a current source proportional to output current when the DC load line function is activated.

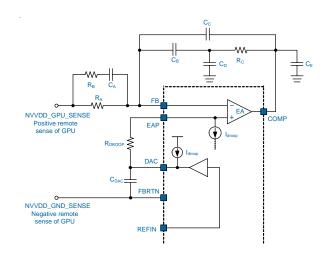


Figure 7. Voltage Control Loop

Output Voltage Differential Sense

The uP9512R uses differential sense by a high-gain low offset error amplifier for output voltage differential sense as shown in Figure 7. The GPU voltage is sensed by the FB and FBRTN pins. FB pin is connected to the positive remote sense pin NVVDD_GPU_SENSE of the GPU via the resistor R_{FB}.FBRTN pin is connected to the negative remote sense pin NVVDD_GND_SENSE of GPU directly.

Power Saving Mode

The uP9512R provides power saving features for platform designers to program platform specific power saving configuration. There are three operation modes: Full-Phase mode, Auto-Phase Shedding mode, and Low-Phase mode. The uP9512R switches between these three operation modes according to the input voltage level of the PSI pin. Figure 8 shows typical PSI application circuit, and Table 2 shows recommended PSI setting voltage level of the three operation modes. In low-phase mode, it can separate into Cold Boot Mode and Warm Boot Mode. The operation phase number of Cold Boot Mode and Warm Boot Mode is



determined by LPC pin. In auto-phase shedding mode, the operation phase number will auto increase/decrease according to output loading. In Full-Phase mode, the maximum phase number of operation is determined by checking the status of CPSx pins when POR.

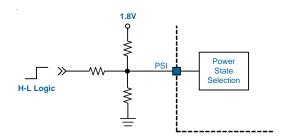


Figure 8. PSI Application Circuit Table 2. Operation Mode and Recommended V_{PSI}

| Operation Mode | Recommended Voltage Setting at PSI |
|--------------------------|---------------------------------------|
| Full-Phase CCM Mode | 1.8V |
| Auto-Phase Shedding Mode | 1V |
| Low-Phase Mode | GND |

Auto-Phase Shedding

The uP9512R provides Auto-Phase Shedding function to reduce the switching and conduction losses at light load condition and enable high efficiency over a wide range of output current. Auto-Phase Shedding function is activated by two conditions:

- 1. PSI voltage stays at "Auto-Phase Shedding Mode".
- After PGOOD goes high, VID pin received the PWM-VID input signal from GPU.

Once the Auto-Phase Shedding function is activated, the uP9512R compares the V_{IMON} with APL1/APL2/APL3/APL4 threshold to decide the operation phase number dynamically. The APL1/APL2/APL3/APL4 threshold and the hysteresis can be programmed through SMBus interface. It also can be programmed by the resistor which is connected from PWM3~PWM6 pins to GND. The APL1 ~ APL4 threshold can be calculated as:

$$V_{APL1} = (10uA \times R_{PWM3}) / 4$$

 $V_{APL2} = (10uA \times R_{PWM4}) / 2$
 $V_{APL3} = (10uA \times R_{PWM5})$
 $V_{APL4} = (10uA \times R_{PWM6})$

If $V_{IMON} < V_{APL1}$, uP9512R operates in single phase;

if $V_{APL1} < V_{IMON} < V_{APL2}$, uP9512R operates in dual phase;

if $V_{APL2} < V_{IMON} < V_{APL3}$, uP9512R operates in four phase;

if $V_{APL3} < V_{IMON} < V_{APL4}$, uP9512R operates in six phase;

if $V_{IMON} > V_{APL4}$, uP9512R operates in eight phase.

The uP9512R always keeps all-of-phase interleaved

operation.

When setting the operating phase number of each current zone, always keep

$$\Phi_{\mathsf{APL1}} < \Phi_{\mathsf{APL2}} < \Phi_{\mathsf{APL3}} < \Phi_{\mathsf{APL4}}.$$

Violating this rule, controller will be forced into full phase operation mode.

The hysteresis of APLx level and the PWM middle state mode can be programmed by a resistor connected from PWM2 pin to GND. When PWM middle state is enabled, the uP9512R drives the PWM middle state voltage by itself. Otherwise, the PWM output of the controller is in high-impedance state, and then the PWM middle state voltage is determined by MOSFET driver. Table 3 lists the recommended $R_{\mbox{\tiny PWM2}}$ value for APL hysteresis and the PWM middle state mode.

Table 3. APL Hysteresis and Recommended R_{PWM2} Value

| Recommended $R_{PWM2}(k\Omega)$ | APL_Hys | PWM Middle State |
|---------------------------------|---------|---------------------|
| 15 | 140mV | |
| 24 | 120mV | |
| 36 | 100mV | |
| 56 | 80mV | Disable |
| 68 | 60mV | |
| 82 | 40mV | |
| 100 | 20mV | |
| 150 | 20mV | |
| 169 | 40mV | |
| 180 | 60mV | |
| 200 | 80mV | Enable |
| 215 | 100mV | |
| 232 | 120mV | |
| 280 | 140mV | |



Operation Frequency and SMBus Device Address

The uP9512R features a multi-function pin (ADDR/FSW) to provide 5 SMBus device address and 8 operation frequency selection. Connect ADDR/FSW pin to 5VCC with a resistor divider (Figure 9) to set the operation frequency and SMBus device address. Table 4 shows the recommended $R_{_{\rm UP}}$ and $R_{_{\rm DW}}$ resistance of the resistor divider.

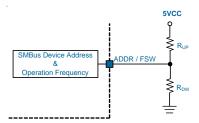


Figure 9. ADDR/FSW Pin Connection

Table 4. Operation Frequency and SMBus Device Address

| | Operation Frequency | SMBus Device Address (Unit: kΩ) | | | | | | | | | |
|-------------------------------------|------------------------|---------------------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|
| V _{ADDR/FSW} = % of 5VCC | | 0x48 | | 0x4A | | 0x4C | | 0x4E | | 0x40 | |
| 70 01 01 00 | (Hz) | R _{UP} | R _{DW} | R _{UP} | R _{DW} | R _{UP} | R _{DW} | R _{UP} | R _{DW} | R _{UP} | R _{DW} |
| 40.63% | 200k | 4.92 | 3.37 | 24.61 | 16.84 | 44.3 | 30.32 | 73.84 | 50.53 | 147.67 | 101.06 |
| 46.88% | 300k | 4.27 | 3.77 | 21.33 | 18.83 | 38.4 | 33.89 | 63.99 | 56.48 | 127.99 | 112.95 |
| 53.13% | 400k | 3.76 | 4.27 | 18.82 | 21.34 | 33.88 | 38.4 | 56.47 | 64.01 | 112.93 | 128.01 |
| 59.38% | 500k | 3.37 | 4.92 | 16.84 | 24.62 | 30.31 | 44.31 | 50.52 | 73.86 | 101.04 | 147.71 |
| 65.63% | 600k | 3.05 | 5.82 | 15.24 | 29.1 | 27.43 | 52.37 | 45.71 | 87.29 | 91.42 | 174.57 |
| 71.88% | 1000k | 2.78 | 7.11 | 13.91 | 35.56 | 25.04 | 64.01 | 41.74 | 106.69 | 83.47 | 213.37 |
| 78.13% | 1500k | 2.56 | 9.14 | 12.8 | 45.72 | 23.04 | 82.3 | 38.4 | 137.17 | 76.8 | 274.35 |
| 84.38% | 2000k | 2.37 | 12.8 | 11.85 | 64.02 | 21.33 | 115.24 | 35.55 | 192.06 | 71.11 | 384.12 |

Phase Number of Operation (Hardware Programming)

The uP9512R supports 8/7/6/5/4/3/2/1-phase operation. The maximum phase number of operation is determined by checking the status of CSPx pins when power on reset. Please follow Table 5 for the phase disable. The maximum phase number of operation is decided and latched at each POR rising edge. The unused PWMx pins can be left floating only if PWM strap function is disabled.

Table 5. Operation Phase Number Settings

| Configuration | Pin Configuration, Pull High to Target | | | | | | | | | | |
|---------------|--|------|------|------|------|------|------|------|--|--|--|
| Configuration | CSP8 | CSP7 | CSP6 | CSP5 | CSP4 | CSP3 | CSP2 | CSP1 | | | |
| 8-phase | | | | | | | | | | | |
| 7-phase | 5VCC | | | | | | | | | | |
| 6-phase | X | 5VCC | | | | | | | | | |
| 5-phase | Х | X | 5VCC | | | | | | | | |
| 4-phase | X | X | Х | 5VCC | | | | | | | |
| 3-phase | X | Х | Х | Х | 5VCC | | | | | | |
| 2-phase | Х | Х | Х | Х | Х | 5VCC | | | | | |
| 1-phase | Х | Х | Х | Х | Х | Х | 5VCC | | | | |

Note 1: "--" denotes normal connection.

Note 2: "x" denotes floating.

Note 3: Use $100k\Omega$ pull up resistor when pull up to 5VCC

Note 4: Strictly follow the table for phase disable. Incorrect pin pull up /down connection may cause catastrophic fault during start up.



Cold Boot and Warm Boot

The uP9512R features programmable operation phase number of Cold Boot Mode and Warm Boot Mode. When PSI=Low and uP9512R first boots up (first time of 5VCC and EN goes high), controller will enter to Cold Boot Mode. Exclude the first boot up condition, when PSI=Low state and controller power up by EN control, then uP9512R will enter to Warm Boot Mode. Connect LPC pin to 5VCC with a voltage divider (Figure 10) to set the operation phase number of Cold Boot Mode and Warm Boot Mode. Figure 11 shows all the power states of uP9512R under each combination of 5VCC/EN/ PSI/VID signal. Table 6 shows the recommended resistance of the voltage divider.

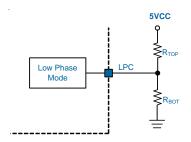


Figure 10. LPC Pin Connection

Table 6. Recommended Resistance of Cold Boot Mode and Warm Boot Mode

| | | Warm Boot Phase Count (Unit: kΩ) | | | | | | | | | | |
|--------------------------|-----------------------|----------------------------------|------------------|------------------|------------------|------------------|------------------|------------------|------------------|------------------|------------------|--|
| $V_{LPC} = \%$ of $5VCC$ | Cold Boot Phase Count | 1-ph | nase | ase 2-ph | | nase 3-ph | | 4-phase | | 5-phase | | |
| | | R _{TOP} | R _{BOT} | R _{TOP} | R _{BOT} | R _{TOP} | R _{BOT} | R _{TOP} | R _{BOT} | R _{TOP} | R _{BOT} | |
| 40.63% | 1-phase | 4.92 | 3.37 | 24.61 | 16.84 | 44.3 | 30.32 | 73.84 | 50.53 | 147.67 | 101.06 | |
| 46.88% | 2-phase | 4.27 | 3.77 | 21.33 | 18.83 | 38.4 | 33.89 | 63.99 | 56.48 | 127.99 | 112.95 | |
| 53.13% | 3-phase | 3.76 | 4.27 | 18.82 | 21.34 | 33.88 | 38.4 | 56.47 | 64.01 | 112.93 | 128.01 | |
| 59.38% | 4-phase | 3.37 | 4.92 | 16.84 | 24.62 | 30.31 | 44.31 | 50.52 | 73.86 | 101.04 | 147.71 | |
| 65.63% | 5-phase | 3.05 | 5.82 | 15.24 | 29.1 | 27.43 | 52.37 | 45.71 | 87.29 | 91.42 | 174.57 | |
| 71.88% | 6-phase | 2.78 | 7.11 | 13.91 | 35.56 | 25.04 | 64.01 | 41.74 | 106.69 | 83.47 | 213.37 | |
| 78.13% | 7-phase | 2.56 | 9.14 | 12.8 | 45.72 | 23.04 | 82.3 | 38.4 | 137.17 | 76.8 | 274.35 | |
| 84.38% | 8-phase | 2.37 | 12.8 | 11.85 | 64.02 | 21.33 | 115.24 | 35.55 | 192.06 | 71.11 | 384.12 | |

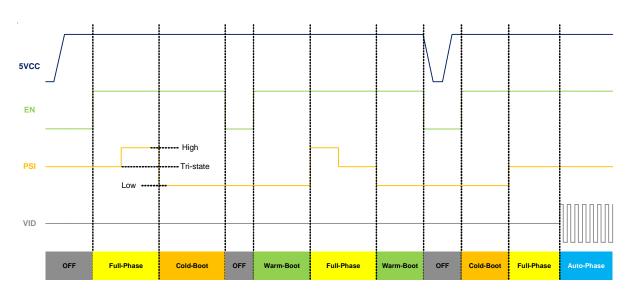


Figure 11. Power States of uP9512R



Channel Current Limit (CH_OC)

The uP9512R adopts channel peak current limit function to avoid catastrophic damage to power stage components.

The controller uses DCR current sensing technique to sense the inductor current (in the form of voltage) in each phase. If the sensed voltage of any phase exceeds the channel current limit threshold, the channel current limit function activates. The resistor $R_{\rm CH\ OC}$ connected between CH_OC pin and GND determines the channel current limit threshold. The channel current limit threshold can be calculated as:

$$I_{OUT(PEAK)} = \frac{R_{CH_OC} \times 20uA}{30 \times R_{DC}}$$

Where $I_{OUT(PEAK)}$ is the per-phase inductor peak current, R_{CH_OC} is the resistor connected between CH_OC pin and $\mbox{GND}.$ The $\mbox{R}_{\mbox{\tiny CH OC}}$ must be at least $10\mbox{k}\Omega.$ Once the perphase current exceeds the setting threshold, the per-phase output inductor current is limited to an average current. A continuous over load event will cause the output voltage drop and eventually trigger under voltage protection and shuts down the uP9512R.

Total Output Current Protection

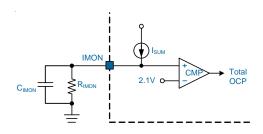


Figure 12. Total Output Current Protection

The uP9512R provides total OCP as shown in Figure 12. A resistor R_{IMON} is connected from IMON pin to GND. The sensed current I_{SUM} is mirrored internally and fed to IMON pin. This current flows through the resistor R_{IMON} creating voltage across it. As the total load current increases, the voltage on IMON pin (V_{IMON}) increases proportionally. When the IMON pin voltage is greater than 2.1V, the total OCP will be triggered. The total OCP level (2.1V) is usually designed for the voltage regulator that is operated in full phase condition by hardware setting. The actual operating phase number is controlled by the PSI signal or the SMBus Auto Phase setting. When the operating phase number is decreased, the total OCP level is decreased as well. The total OCP level is changed per actual operating phase number. Table 7 shows the relationship between total OCP ratio per actual operating phase number and the hardware configuration. The total output current (I_{OUT MAX}) of triggered OCP is calculated as:

$$I_{OUT_MAX} = \frac{V_{OCP} - 0.1V}{R_{IMON}} \times \frac{N \times R_{SUM}}{R_{DC}}$$

The IMON pin has a 0.1V offset voltage, which means the IMON voltage increases from 0.1V as load current increases. The resistor R_{IMON} must be in the range of $10k\Omega$ to $60k\Omega$. To ensure correct operation of the 0.1V offset mechanism, care must be taken when adding a capacitor to the IMON pin to adjust the IMON response time. The RC time constant must be adequate to ensure normal operation. Take $R_{IMON} \times C_{IMON} < 1u$ as the rule of thumb when determining maximum C_{IMON}.

Once the total OCP is triggered. The uP9512R will turn off both high-side and low-side MOSFETs of all channels. The total OCP function is a latch-off function and only EN restart or 5VCC re-POR can release the latch. Table 7. Total OCP and Operating Phase Number

| Total Output OCP Ratio | | Operating Condition | | | | | | | | | |
|------------------------|------------------------|---------------------|---------|---------|---------|---------|---------|---------|---------|--|--|
| iotai Output | iolai Oulpul OCP Ratio | | 7-phase | 6-phase | 5-phase | 4-phase | 3-phase | 2-phase | 1-phase | | |
| | 8-phase | 1 | 7/8 | 3/4 | 5/8 | 1/2 | 3/8 | 5/16 | 2/8 | | |
| | 7-phase | | 1 | 7/8 | 3/4 | 5/8 | 1/2 | 3/8 | 5/16 | | |
| | 6-phase | | | 1 | 3/4 | 5/8 | 1/2 | 3/8 | 5/16 | | |
| Hardware | 5-phase | | | | 1 | 3/4 | 5/8 | 1/2 | 3/8 | | |
| Configuration | 4-phase | | | | | 1 | 3/4 | 1/2 | 3/8 | | |
| | 3-phase | | | | | | 1 | 3/4 | 1/2 | | |
| | 2-phase | | | | | | | 1 | 3/4 | | |
| | 1-phase | | | | | | | | 1 | | |



Ramp Slope Setting

The ramp slope of the oscillator for PWM modulation can be adjusted and is determined by the resistor R_{PWM7} . The setting for ramp slope and recommended R_{PWM7} resistance is shown in the table below.

| R _{PWM7} | Ramp Slope |
|-------------------|------------|
| 39kΩ | 50% |
| 100kΩ | 75% |
| 150kΩ | 100% |
| unstuffed | 125% |

Thermal Protection (TSENSE)

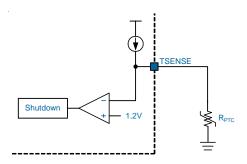


Figure 13. PTC Mode Circuit Connection

The uP9512R features a TSENSE pin to monitor the thermal condition of regulator. The uP9512R TSENSE pin supports positive temperature coefficient (PTC) thermistor protection network. Connect a PTC thermistor from TSENSE pin to GND to implement this function as shown in Figure 13. The PTC thermistor is placed close to the hottest point of the regulator, normally close to the inductor and the low-side MOSFET of phase1. A precision 120uA current source flows out from the TSENSE pin through the PTC thermistor and creates a voltage V_{TSENSE} on this pin. As regulator temperature rises, the V_{TSENSE} increases. If the V_{TSENSE} is higher than the1.2V, the controller shuts down.

Over Voltage Protection (OVP)

The OVP is triggered if $V_{FB} > 1.5 x \, V_{EAP}$ sustained 5us.When OVP is activated, the uP9512R turns on all low-side MOSFETs and turns off all high-side MOSFETs. The over voltage protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

Under Voltage Protection (UVP)

The under voltage protection is triggered if $V_{FB} < 0.5 \text{ x V}_{EAP}$ sustained 5us. When UVP is activated, the uP9512R turns off all high-side and low-side MOSFETs. The under voltage protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

Over Temperature Protection (OTP)

The uP9512R monitors the temperature of itself. If the temperature exceeds typical 160°C, the uP9512R is forced into shutdown mode. The over temperature protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

SMBus (SCL & SDA)

The uP9512R features an SMBus interface to allow user to adjust various operating parameters. The supported operating parameters that can be adjusted through the SMBus are summarized as Table 8. The main function is to dynamically change the offset voltage, switching frequency, operating phase number, and load line according to the total load current. This function is referred to Auto Phase, and it provides user the maximal flexibility in the platform design to maximize voltage regulator's efficiency and performance as well. The SMBus interface default is locked, it can be "read only" before it is unlocked. It writes 94h value in the register 0x39h to unlock the SMBus and writes 87h value to lock the SMBus interface. The SMBus provides one time lock/unlock mechanism. Once it is unlocked and locked, it cannot be unlocked again. It can only be reset by 5VCC re-cycle.

If the SMBus interface is not available in the platform design, the SDA and SCL pins can also be the hardware programming pins to program the operation mode when controller is working in single-phase operation. The uP9512R detects the state of SCL and SDA pins right on power on reset (POR) to recognize whether the SMBus is used or SCL and SDA becomes hardware programming pins. If SCL pin is "high" when POR, it becomes SMBus programming pins and the controller latched at CCM operation mode when controller is working in single-phase operation. If the SCL pin is "low" when POR, it becomes hardware programming pins and the controller latched at DCM mode when controller is working in single-phase operation. Then, the SDA pin is used to program the PWM output behavior of DCM operation mode as the following table.

| SCL | SDA | Single Phase Operation Mode |
|-----|-----|------------------------------|
| 0 | 0 | Controller Controlled ZCD |
| 0 | 1 | MOSFET Driver Controlled ZCD |
| 1 | х | Forced CCM Mode |

"0": Denotes the voltage is lower than 1V

"1": Denotes the voltage is higher than 1.2V

"x": Don't care



When SCL=0 and SDA=0, the zero current detection (ZCD) is controlled by uP9512R controller. When the zero inductor current is detected, the controller sets the PWM output from low to high impedance state or sets PWM output to middle state level (depends on PWM2 setting) and turns off the low side MOSFET, then the controller runs in discontinuous conduction mode (DCM). When SCL=0 and SDA=1, the zero current detection is controlled by MOSFET driver itself. The uP9512R sets the PWM output from high to middle state level after a effective PWM duty cycle. When the companion MOSFET driver receives the PWM middle voltage from uP9512R controller, the MOSFET driver decides the discontinuous conduction mode (DCM) or continuous conduction mode (CCM) by itself according to output loading.

APL1, APL2, APL3, APL4 : (Reg0x01 ~ Reg0x04)

Define the thresholds for five load current states (LCS0, LCS1, LCS2, LCS3 and LCS4). The controller compares the APL1, APL2, APL3 and APL4 content with V_{IMON} voltage to determine which load current state should be entered and executes the corresponding operating parameter settings (frequency, offset, operating phase number and load line).

LCS0: V_{IMON}> APL4, highest load current state.

LCS1 : $APL4 > V_{IMON} > APL3$

LCS2: APL3 > $V_{\rm IMON}$ > APL2 LCS3: APL2 > $V_{\rm IMON}$ > APL1 LCS4: APL1 > $V_{\rm IMON}$, lowest load current state. APL_Hys1, APL_Hys2, APL_Hys3, APL_Hys4: $(Reg0x05\sim Reg0x06)$

Define the hysteresis voltage of APL1, APL2, APL3 and APL4. 8-bits content setting with 20mV/step

IICP0, IICP1, IICP2, IICP3, IICP4:

$(Reg0x07 \sim Reg0x09)$

Define the operating phase number in each load current state. The operating phase number can be full-phase to single phase.

VOFS0, VOFS1, VOFS2, VOFS3, VOFS4:

(Reg0x0A~Reg0x0C)

Define the offset voltage in each load current state. 4-bits content setting with 10mV/step.

IICF0, IICF1, IICF2, IICF3, IICF4:

$(Reg0x0D \sim Reg0x0F)$

Define the switching frequency in each load current state. The switching frequency is defined as the ratio to current operation frequency setting.

Current Balance Gain Adjustment:

(Reg0x12 ~ Reg0x19)

The uP9512R provides the current balance gain adjustment for user to optimize the performance in the system application. The current balance gain adjustment is defined as the ratio to default setting.

Current Balance Offset Adjustment: $(Reg0x1A \sim Reg0x1D)$

uP9512R features the current balance offset adjustment for user the optimize the performance in the system application.3-bits content setting with 0.4uA/step.

Channel Current Limit (CH OC): (Reg0x22)

For per-channel current limit threshold adjustment. 8-bits content setting with 10mV/step.

Total OCP : (Reg0x23)

For total output current protection level adjustment. 8-bits content setting with 10mV/step. The total output current protection adjustment is defined as the ratio to default setting.

T OCP/UV/OV: (Reg0x24)

T OCP programs the delay time of total OCP. UV/OV is used for the threshold adjustment of UVP and OVP respectively.

GCOMP: (Reg0x26)

For OTA transconductance setting for voltage control loop. It is defined as the ratio to the default value of 1960uA/V.

SL_RAMP: (Reg0x3A)

The slope adjustment of the RAMP signal. It is defined as the ratio to the default setting.

IOUT: (Reg0x2C)

This register reports total output current that is converted by internal ADC with 10mV/step.

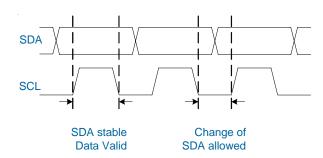
VOUT: (Reg0x2D)

This register reports total output voltage that is converted by internal ADC with 10mV/step.



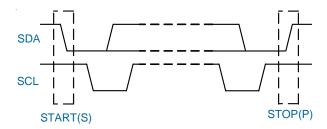
Data Validity

The data on the SDA line must be stable during the HIGH period of the SCL, unless generating a START or STOP condition. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW. Refer to the figure below.



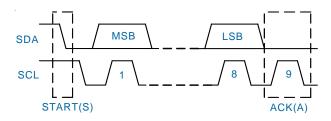
START and STOP Conditions

A START (S) condition is a HIGH to LOW transition of SDA while SCL is HIGH. The STOP (P) condition is a LOW to HIGH transition of SDA while SCL is HIGH. A STOP condition must be sent before each START condition.



Acknowledge

Each address and data transmission uses 9 clock pulses. The ninth pulse is the acknowledge bit (A). After the start condition, the master sends 7 slave address bits and a R/W bit during the next 8 clock pulses. During the ninth clock pulse, the device that recognizes its own address pulls SDA low to acknowledge. The acknowledge bit is also used by both the master and the slave to acknowledge receipt of register addresses and data.



Read and Write Protocol

Write to a Single Register

| S | slave_addr+W | AS | reg_addr | AS | reg_data | AS | Р | |
|---|--------------|----|----------|----|----------|----|---|--|
|---|--------------|----|----------|----|----------|----|---|--|

Read from a Single Register

| S | slave_addr+W | AS | reg_addr | AS | S | slave_addr+R | AS | reg_data | NA | Р |
|---|--------------|----|----------|----|---|--------------|----|----------|----|---|
|---|--------------|----|----------|----|---|--------------|----|----------|----|---|

S = START, P = STOP, AS = ACK from slave, AM = ACK from master, NA = No ACK



Table 8. SMBus Configuration Register

| Register Address | Register Name | Access | Default | Description |
|---------------------|--|--------|---------|---|
| 0x01 | APL1[7:0] | R/W | 00h | Set Auto Phase Shedding Threshold 1 0V ~ 630mV(10mV / step) V _{MON} < V _{APL1} => LCS4 (lowest load current state) |
| 0x02 | APL2[7:0] | R/W | 00h | Set Auto Phase Shedding Threshold 2 0V ~1.27V(10mV / step) V _{APL1} < V _{IMON} < V _{APL2} => LCS3 |
| 0x03 | APL3[7:0] | R/W | 00h | Set Auto Phase Shedding Threshold 3 0V ~ 2.55V(10mV / step) V _{APL2} < V _{IMON} < V _{APL3} => LCS2 |
| 0x04 | APL4[7:0] | R/W | 00h | Set Auto Phase Shedding Threshold 4, $0V \sim 2.55V(10mV / step)$ $V_{APL3} < V_{MON} < V_{APL4} => LCS1$ $V_{MON} > V_{APL4} => LCS0$ (highest load current state) |
| 0x05 | PWM_Mid[7] APL_Hys1[6:4] APL_Hys2[2:0] | R/W | 55h | Bit[3]: Don't care. PWM_Mid[7]: Controller driving PWM middle state voltage "0": Disable"1": Enable APL_Hys1[6:4]: Hysteresis of APL1 threshold 0mV ~ 140mV (20mV / step) APL_Hys2[2:0]: Hysteresis of APL2 threshold 0mV ~ 140mV (20mV / step) |
| 0x06 | APL_Hys3[6:4] APL_Hys4[2:0] | R/W | 55h | Bit[7] & Bit[3] : Don't Care. APL_Hys3[6:4] : Hysteresis of APL3 threshold 0mV ~ 140mV (20mV / step) APL_Hys4[2:0] : Hysteresis of APL4 threshold 0mV ~ 140mV (20mV / step) |
| 0x07 | IICP0[6:4] IICP1[2:0] | R/W | 75h | Bit[7] & Bit[3]: Don't care. IICP0[6:4]: Operation phase number of LCS0. Default = 8-phase IICP1[2:0]: Operation phase number of LCS1. Default = 6-phase 000: 1 phase; 001: 2 phase; 010: 3 phase; 011: 4 phase 100: 5 phase; 101: 6 phase; 110: 7 phase; 111: 8 phase |
| 0x08 | IICP2[6:4] IICP3[2:0] | R/W | 31h | Bit[7] & Bit[3]: Don't care. IICP2[6:4]: Operation phase number of LCS2. Default = 4-phase IICP3[2:0]: Operation phase number of LCS3. Default = 2-phase 000: 1 phase; 001: 2 phase; 010: 3 phase; 011: 4 phase 100: 5 phase; 101: 6 phase; 110: 7 phase; 111: 8 phase |
| 0x09 | IICP4[6:4] | R/W | 00h | Bit[7] & Bit[3:0] : Don't care. IICP4[6:4] : Operation phase number of LCS4. Default = 1-phase 000 : 1 phase ; 001 : 2 phase ; 010 : 3 phase ; 011 : 4 phase 100 : 5 phase ; 101 : 6 phase ; 110 : 7 phase ; 111 : 8 phase |
| 0x0A | IICV0[7:4] IICV1[3:0] | R/W | 00h | IICV0[7:4]: Voltage offset of LCS0. 0mV ~ 150mV(10mV / step). Default = 0mV IICV1[3:0]: Voltage offset of LCS1. 0mV ~ 150mV(10mV / step). Default = 0mV |



| Register Address | Register Name | Access | Default | Description |
|---------------------|----------------------------|--------|---------|---|
| 0x0B | IICV2[7:4] IICV3[3:0] | R/W | 00h | IICV2[7:4]: Voltage offset of LCS2. 0mV ~ 150mV(10mV / step). Default = 0mV IICV3[3:0]: Voltage offset of LCS3. 0mV ~ 150mV(10mV / step). Default = 0mV |
| 0x0C | IICV4[7:4] | R/W | 00h | Bit[3:0] : Don't care. IICV4[7:4] : Voltage offset of LCS4. OmV ~ 150mV(10mV / step). Default = 0mV |
| 0x0D | IICF0[7:4] IICF1[3:0] | R/W | 88h | IICF0[7:4]: Operation frequency of LCS0. IICF1[3:0]: Operation frequency of LCS1. 0000: 60%; 0001: 65%; 0010: 70%; 0011: 75%; 0100: 80%; 0101: 85%; 0110: 90%; 0111: 95%; 1000: 100% (default); 1001: 125%; 1010: 150%; 1011: 175%; 1100: 200%; 1101: 225%; |
| 0x0E | IICF2[7:4] IICF3[3:0] | R/W | 88h | IICF2[7:4]: Operation frequency of LCS2. IICF3[3:0]: Operation frequency of LCS3. 0000: 60%; 0001: 65%; 0010: 70%; 0011: 75%; 0100: 80%; 0101: 85%; 0110: 90%; 0111: 95%; 1000: 100% (default); 1001: 125%; 1010: 150%; 1011: 175%; 1100: 200%; 1101: 225%; |
| 0x0F | IICF4[7:4] IICLL0[2:0] | R/W | 84h | Bit [3]: Don't care. IICF4[7:4]: Operation frequency of LCS4. 0000: 60%; 0001: 65%; 0010: 70%; 0011: 75%; 0100: 80%; 0101: 85%; 0110: 90%; 0111: 95%; 1000: 100% (default); 1001: 125%; 1010: 150%; 1011: 175%; 1100: 200%; 1101: 225%; 1110: 250%; 1111: 275% IICLL0[2:0]: Load line setting of LCS0. 000: 0%; 001: 25%; 010: 50%; 011: 75% 100:100%(default); 101: 125%; 110: 150%; 111: 175% |
| 0x10 | IICLL1[6:4] IICLL2[2:0] | R/W | 44h | Bit[7] & Bit[3] : Don't care. IICLL1[6:4] : Load line setting of LCS1. IICLL2[2:0] : Load line setting of LCS2. 000 : 0%; 001 : 25%; 010 : 50%; 011 : 75%; 100 :100%(default); 101 : 125%; 110 : 150%; 111 : 175% |
| 0x11 | IICLL3[6:4] IICLL4[2:0] | R/W | 44h | Bit[7] & Bit[3] : Don't care. IICLL3[6:4] : Load line setting of LCS3. IICLL4[2:0] : Load line setting of LCS4. 000 : 0%; 001 : 25%; 010 : 50%; 011 : 75%; 100 :100%(default); 101 : 125%; 110 : 150%; 111 : 175% |



| Register Address | Register Name | Access | Default | Description |
|---------------------|------------------------------|--------|---------|--|
| 0x12 | CB_EN[7] PH8_IGAIN[6:2] | R/W | BCh | Bit[1:0]: Don't care. CB_EN[7]: On/Off control of current balance function, defaule on. "0" = OFF (current balance function is disabled) "1" = ON (current balance function is enabled) PH8_IGAIN[6:2]: PHASE8 current balance gain adjustment PH8_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x13 | PH7_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH7_IGAIN[6:2] : PHASE7 current balance gain adjustment PH7_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x14 | PH6_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH6_IGAIN[6:2] : PHASE6 current balance gain adjustment PH6_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x15 | PH5_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH5_IGAIN[6:2] : PHASE5 current balance gain adjustment PH5_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x16 | PH4_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH4_IGAIN[6:2] : PHASE4 current balance gain adjustment PH4_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x17 | PH3_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH3_IGAIN[6:2] : PHASE3 current balance gain adjustment PH3_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x18 | PH2_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH2_IGAIN[6:2] : PHASE2 current balance gain adjustmen PH2_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x19 | PH1_IGAIN[6:2] | R/W | 3Ch | Bit[7] & Bit[1:0] : Don't care. PH1_IGAIN[6:2] : PHASE1 current balance gain adjustment PH1_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%. |
| 0x1A | PH8_IOS[6:4] PH7_IOS[2:0] | R/W | 00h | Bit[7] & Bit[3]: Don't care. PH8_IOS[6:4]: PHASE8 current balance offset adjustment, default = 0uA. PH7_IOS[2:0]: PHASE7 current balance offset adjustment, default = 0uA. 000: 0uA; 001: 0.4uA; 010: 0.8uA; 011: 1.2uA; 100: 1.6uA; 101: 2.0uA; 110: 2.4uA; 111: 2.8uA |
| 0x1B | PH6_IOS[6:4] PH5_IOS[2:0] | R/W | 00h | Bit[7] & Bit[3] : Don't care. PH6_IOS[6:4] : PHASE6 current balance offset adjustment, default = 0uA. PH5_IOS[2:0] : PHASE5 current balance offset adjustment, default = 0uA. 000 : 0uA; 001 : 0.4uA; 010 : 0.8uA; 011 : 1.2uA; 100 : 1.6uA; 101 : 2.0uA; 110 : 2.4uA; 111 : 2.8uA |
| 0x1C | PH4_IOS[6:4] PH3_IOS[2:0] | R/W | 00h | Bit[7] & Bit[3] : Don't care. PH4_IOS[6:4] : PHASE4 current balance offset adjustment default = 0uA. PH3_IOS[2:0] : PHASE3 current balance offset adjustment default = 0uA. 000 : 0uA; 001 : 0.4uA; 010 : 0.8uA; 011 : 1.2uA; 100 : 1.6uA; 101 : 2.0uA; 110 : 2.4uA; 111 : 2.8uA |



| Register Address | Register Name | Access | Default | Description |
|---------------------|--------------------------------|--------|---------|--|
| 0x1D | PH2_IOS[6:4] PH1_IOS[2:0] | R/W | 00h | Bit[7] & Bit[3]: Don't care. PH2_IOS[6:4]: PHASE2 current balance offset adjustment, default = 0uA. PH1_IOS[2:0]: PHASE1 current balance offset adjustment, default = 0uA. 000: 0uA; 001: 0.4uA; 010: 0.8uA; 011: 1.2uA; 100: 1.6uA; 101: 2.0uA; 110: 2.4uA; 111: 2.8uA |
| 0x1E | POCGAIN8[7:4] POCGAIN7[3:0] | R/W | BBh | POCGAIN8[7:4]: PHASE8 channel current limit gain adjustment, default = 100%. POCGAIN7[3:0]: PHASE7 channel current limit gain adjustment, default = 100%. 0000: 237.5%; 0001: 225%; 0010: 212.5%; 0011: 200%; 0100: 187.5%; 0101: 175%; 0110: 162.5%; 0111: 150%; 1000: 137.5%; 1001: 125%; 1010: 112.5%; 1011: 100%; 1100: 87.5%; 1101: 75%; 1110: 62.5%; 1111: 50% |
| 0x1F | POCGAIN6[7:4] POCGAIN5[3:0] | R/W | BBh | POCGAIN6[7:4]: PHASE6 channel current limit gain adjustment, default = 100%. POCGAIN5[3:0]: PHASE5 channel current limit gain adjustment, default = 100%. 0000: 237.5%; 0001: 225%; 0010: 212.5%; 0011: 200%; 0100: 187.5%; 0101: 175%; 0110: 162.5%; 0111: 150%; 1000: 137.5%; 1001: 125%; 1010: 112.5%; 1011: 100%; 1100: 87.5%; 1101: 75%; 1110: 62.5%; 1111: 50% |
| 0x20 | POCGAIN4[7:4] POCGAIN3[3:0] | R/W | BBh | POCGAIN4[7:4]: PHASE4 channel current limit gain adjustment, default = 100%. POCGAIN3[3:0]: PHASE3 channel current limit gain adjustment, default = 100%. 0000: 237.5%; 0001: 225%; 0010: 212.5%; 0011: 200%; 0100: 187.5%; 0101: 175%; 0110: 162.5%; 0111: 150%; 1000: 137.5%; 1001: 125%; 1010: 112.5%; 1011: 100%; 1100: 87.5%; 1101: 75%; 1110: 62.5%; 1111: 50% |
| 0x21 | POCGAIN2[7:4] POCGAIN1[3:0] | R/W | BBh | POCGAIN2[7:4]: PHASE2 channel current limit gain adjustment, default = 100%. POCGAIN1[3:0]: PHASE1 channel current limit gain adjustment, default = 100%. 0000: 237.5%; 0001: 225%; 0010: 212.5%; 0011: 200%; 0100: 187.5%; 0101: 175%; 0110: 162.5%; 0111: 150%; 1000: 137.5%; 1001: 125%; 1010: 112.5%; 1011: 100%; 1100: 87.5%; 1101: 75%; 1110: 62.5%; 1111: 50% |
| 0x22 | CH_OC[7:0] | R/W | | CH_OC[7:0]: Channel current limit threshold adjustment. V _{CH_OC} = Bit[7:0] x 10mV |
| 0x23 | Total_OCP[2:0] | R/W | 00h | Bit [7:3] : Don't care. Total_OCP[2:0] : Total output current protection threshold adjustment. 000 : 100% (default) ; 001 : 001% ; 010 : 120% ; 011 : 130% 100 : 140% ; 101 : 150% ; 110 : 160% ; 111 : 170% |



| Register Address | Register Name | Access | Default | Description |
|---------------------|--|--------|---------|---|
| 0x24 | T_OCP[7:6] UV[5:3] OV[2:0] | R/W | 1Bh | T_OCP[7:6]: Total output current protection delay time adjustment. 00: 20us (default); 01: 10us; 10: 6.67us; 11: 5us UV[5:3]: Under voltage protection threshold adjustment. 000: 30%; 001: 35%; 010: 40%: 011: 45% (default) 100: 50%; 101: 55%; 110: 60%; 111: 65% OV[2:0]: Over voltage protection threshold adjustment. 000: 140%; 001: 145%; 010: 150%: 011: 155% (default) 100: 160%; 101: 165%; 110: 170%; 111: 175% |
| 0x26 | GCOMP[3:0] | R/W | 00h | Bit[7:4]: Don't care. GCOMP[3:0]: OTA Gm value selection, default = 1960uA/V. 000: 1960uA/V; 001: 2300uA/V; 010: 2610uA/V; 011: 2890uA/V; 100: 3380uA/V; 101: 1580uA/V; 110: 1150uA/V; 111: 636uA/V |
| 0x2A | Misc2[6:2] | R/W | 20h | Bit[7] & Bit[1:0]: Internal testing bit. Keep these bit values = "0". Bit[6]: Output voltage offset enable control "0" = Disable Offset(default) "1" = Enable Offset Bit[5]: Auto Phase H/W setting enable control "0" = Ignore H/W setting "1" = Follow H/W setting (default) Bit[4]: Auto Phase enable control (when Bit[5]=0) "0" = Disable Auto Phase (forced full phase operation) (default) "1" = Enable Auto Phase Bit[3]: DCM enable control when in 1-phase operation "0" = Disable DCM (default) "1" = Enable DCM Bit[2]: Forced full phase operation when channel OCL is triggered at APS Mode. "0" = Disable (default) "1" = Enable |
| 0x2C | IOUT[7:0] | RO | | Total output current reporting, ADC result of IMON voltage. (10mV/step) |
| 0x2D | VOUT[7:0] | RO | | Output voltage reporting. (sense VOUT voltage) (10mV/step) |
| 0x33 | ZC_OFFSET[7:5] T_PH_DW[4:2] OTP[1] | R/W | 26h | Bit[0]: Internal testing bit. Keep this bit value = "0". ZC_OFFSET[7:5]: ZC offset adjustment. 000=0mV; 001=1mV; 010=2mV; 011=3mV; 100=4mV 101=5mV; 110=6mV; 111=7mV T_PH_DW[4]: Down phase delay control. "0": Disable (default) "1": Enable T_PH_DW[3:2]: Down phase delay time 00=10us 01=20us(default) 10=40us 11=80us OTP[1]: OTP protection control. "0": Disable "1": Enable (default) |



| Register Address | Register Name | Access | Default | Description |
|---------------------|---|--------|---------|--|
| 0x35 | PROT_IND2[7:0] | RO | 00h | Each channel OCL indicator. Bit[7]: PHASE8 channel OCL indicator Bit[6]: PHASE7 channel OCL indicator Bit[5]: PHASE6 channel OCL indicator Bit[4]: PHASE5 channel OCL indicator Bit[3]: PHASE4 channel OCL indicator Bit[2]: PHASE3 channel OCL indicator Bit[1]: PHASE2 channel OCL indicator Bit[0]: PHASE1 channel OCL indicator "0" = Not Active "1" = Active |
| 0x37 | PWM1_H_Mid[2] BF[1] | R/W | 02h | Bit[7:3] & Bit[0]: Internal testing bit. Keep these bit values = "0". PWM1_H_Mid[2]: PWM1 output switching behavior control. Once it is enabled, only PWM1 output switching behavior changes from "High -> Low" to "High -> Middle", other PWM outputs keep "High -> Low" switching behavior. "0": Disable (default) "1": Enable BF[1]: Beat Frequency Function "0": Disable "1": Enable (default) |
| 0x38 | ACLL[7:5] V_OCL_MIN[4:2] IOUT_AVG_SR[1:0] | R/W | 2Ch | Bit[7]: AC load line control. "0": Follow HW setting (default) "1": Enable AC Load Line Bit[6:5]: AC load line response time 00=40us 01=80us(default) 10=120us 11=160us Bit[4]: OCL disable if REFIN < V_OCL_Min "0" = Disable(default) "1" = Enable Bit[3:2]: OCL disable if REFIN voltage reaches below threshold. "00"=0.3V; "01"=0.4V; "10"=0.5V; "11"=0.6V(default) Bit[1:0]: Sample rate of IOUT_AVG. "00"=50us(default); "01"=200us; "10"=800us; "11"=3200us |
| 0x39 | SMBus_Lock[7:0] | R/W | 00h | SMBus_Lock[7:0]: SMBus register security lock. SMBus register default is locked, all the registers are "read only" and cannot be modified before unlock. Once the SMBus unlock and lock again, it needs VCC re-POR to reset. Bit[7:0] = "94h", unlock SMBus Bit[7:0] = "87h", lock SMBus |
| 0x3A | SL_RAMP[7:6] | R/W | C0h | Bit[5:0] : Don't care. SL_RAMP[7:6] :RAMP slope adjustment. 00 : 01 : 75% ; 10 : 100% ; 11 : 125%(default) |



| Register Address | Register Name | Access | Default | Description |
|---------------------|---------------------------------|--------|---------|--|
| 0x3B | PROT_IND[7:3] OP_PH_MON[2:0] | RO | 00h | Protection indication, indicating which protection is triggered. Bit[7]: OTP indicator "0" = Not Active "1" = Active Bit[6]: Total OCP Indicator "0" = Not Active "1" = Active Bit[5]: Channel OCL indicator "0" = Not Active "1" = Active Bit[4]: OVP Indicator "0" = Not Active "1" = Active Bit[3]: UVP Indicator "0" = Not Active "1" = Active Bit[3]: OVP Indicator "0" = Not Active "1" = Active Bit[2:0]: Operating Phase Number Monitor 000: 1 phase; 001: 2 phase; 010: 3 phase; 011: 4 phase 100: 5 phase; 101: 6 phase; 110: 7 phase; 111: 8 phase |
| 0x3C | Misc1[3:0] | R/W | 0Fh | Bit[7:5]: Don't care. Bit[4]: Internal testing bit. Keep this bit value = "0". Bit[3]: Total OCP control "0" = Disable Total OCP function "1" = Enable Total OCP function(default) Bit[2]: Channel OCL Control "0" = Disable Channel OCL function "1" = Enable Channel OCL function(default) Bit[1]: OVP Control "0" = Disable OVP function "1" = Enable OVP function(default) Bit[0]: UVP Control "0" = Disable UVP function "1" = Enable UVP function |
| 0x3D | IOUT_AVG[7:0] | RO | 00h | Average output current report, ADC result of V _{IMON.} (10mV/step) |
| 0x27 | Vendor ID | RO | 00h | |
| 0x28 | Device ID | RO | 2Bh | |



| | Absolute Maximum Rating |
|--|------------------------------------|
| (Note 1) | |
| Supply Input Voltage, 5VCC | |
| Other Pins | 0.3V to +6V |
| Storage Temperature Range | |
| • | 150°C |
| Lead Temperature (Soldering, 10 sec) | 260°C |
| ESD Rating (Note 2) | |
| HBM (Human Body Mode) | 2kV |
| | Thermal Information |
| Package Thermal Resistance (Note 3) | |
| · , , | 36°C/W |
| | 3°C/W |
| Power Dissipation, $P_D @ T_A = 25^{\circ}C$ | |
| . B // | 2.78W |
| | Recommended Operation Conditions |
| (Note 4) | - Recommended operation conditions |
| Operating Junction Temperature Range | |
| Operating Ambient Temperature Range | |
| Supply Input Voltage, 5VCC | 4.5V to 5.5V |
| Power Stage Input Voltage, V _{IN} | 3V to 20V |

- **Note 1.** Stresses listed as the above *Absolute Maximum Ratings* may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.
- Note 2. Devices are ESD sensitive. Handling precaution recommended.
- Note 3. θ_{JA} is measured in the natural convection at $T_A = 25^{\circ}\text{C}$ on a low effective thermal conductivity test board of JEDEC 51-3 thermal measurement standard.
- **Note 4.** The device is not guaranteed to function outside its operating conditions.



Electrical Characteristics

 $(5VCC = 5V, T_A = 25^{\circ}C, unless otherwise specified)$

| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|----------------------------------|-------------------------|--|------|-----|------|------|
| Supply Input | | | l | | | |
| 5VCC POR Threshold | POR _{5VCC} | 5VCC rising | 4 | 4.3 | 4.5 | V |
| 5VCC POR Hysteresis | HYS _{5VCC_POR} | | | 300 | | mV |
| Quiescent Current | I _Q | EN = high , No switching | | 7 | | mA |
| Shutdown Current | I _{SD} | EN = 0V | | 300 | | uA |
| Power Stage Input Voltage Monit | oring | | • | | | |
| VINMON Monitoring Range | | | 0.3 | | 2.4 | V |
| VINMON Rising Threshold | V _{VINMON} | | | 0.2 | | V |
| VINMON Hysteresis | V _{VINMON_HYS} | | | 100 | | mV |
| Enable Control | | | | | | |
| Logic Low | V _{IL_EN} | | | | 0.1 | V |
| Logic High | V _{IH_EN} | | 0.2 | | | V |
| PWMVID Interface (VREF, VID, RE | | N) | - | | | |
| VREF Voltage Accuracy | V _{REF} | | 1.98 | 2 | 2.02 | V |
| VREF Sourcing Current | I _{REF_SRC} | VREF short to GND | 10 | | | mA |
| REFIN Disable Threshold | V _{REFIN_DSB} | | | 0.1 | | V |
| External Reference Voltage Range | V _{REFIN} | | 0.2 | | 2 | V |
| VID Input Low | $V_{\text{IL_VID}}$ | | | | 0.6 | V |
| VID Input High | V _{IH_VID} | | 1.2 | | | V |
| VID Tri-state Voltage | V _{TRI_VID} | | | 0.9 | | V |
| VID Tri-state Delay | T _{TRI_VID} | VID from High to Tri-state; VID from Low to Tri-state | | 100 | | ns |
| REFADJ Source Resistance | R _{BF_SRC} | I _{SRC} = 1mA | | 20 | | Ω |
| REFADJ Sink Resistance | R _{BF_SNK} | I _{SINK} = 1mA | | 20 | | Ω |
| DAC Voltage Accuracy | | | -! | ! | | |
| DAC Output Accuracy | V _{DAC} | Load Line Disabled | -1 | | 1 | mV |
| Oscillator | | | ' | | | |
| Operation Frequency Range | F _{sw} | Per-phase operation frequency | 200 | | 2000 | kHz |
| Frequency Accuracy | | Frequency setting to 300kHz | 270 | 300 | 330 | kHz |
| Maximum Duty Cycle | D _{MAX} | Ramp slope setting to 100% | | 45 | | % |
| Minimum PWM Pulse Width | T _{PWM_MIN} | Guaranteed by design | | 40 | | ns |



Electrical Characteristics

| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|--------------------------------|----------------------|---|-----|------|-----|--------|
| Soft-Start | | | - | • | | |
| Output Ramp Up Time | T _{RAMP} | R _{PWM8} = unstuffed | | 640 | | us |
| Initialization Time | T _{INIT} | EN go high to Vout start up from 0V | | 550 | | us |
| Error Amplifier | | | • | | | |
| Offset Voltage | V _{OS(EA)} | | -1 | | 1 | mV |
| Input Bias Current | I _{EA} | Guaranteed by design | -10 | | 10 | nA |
| Open Loop DC Gain | AO | Guaranteed by design | | 70 | | dB |
| Gain-Bandwidth Product | GBW | Guaranteed by design | | 10 | | MHz |
| Trans-conductance | GM | | | 1960 | | uA / V |
| COMP Source Current | COMP_SRC | | | 300 | | uA |
| COMP Sink Current | COMP_SNK | | | 300 | | uA |
| FBRTN | | | | | | |
| FBRTN Current | I _{FBRTN} | EN = 1.8V, normal operation | | | 100 | uA |
| Current Summing Amplifier (CS | PSUM & C | SNSUM) | | | | |
| Input Offset Voltage | V _{OFF_CSA} | Guaranteed by design | -1 | | 1 | mV |
| Max Sourcing Current | I _{SRC_CSA} | | 300 | | | uA |
| Current Sense Amplifier (CSP1 | ~CSP8) | | • | | | • |
| Input Offset Voltage | V _{OFF_CSA} | Guaranteed by design | -1 | | 1 | mV |
| PWM Output (PWM1~PWM8) | | | • | | | |
| Output Low Voltage | V _{PWM_L} | $I_{SNK} = 4mA$ | | | 0.2 | V |
| Output Hight Voltage | V _{PWM_H} | I _{SOURCE} = 4mA | 4.7 | | | V |
| High Impedance State Leakage | | V _{PWM} = 0V | -1 | | 0 | uA |
| | | V _{PWM} = 5V | 0 | | 1 | uA |
| Source Current | I _{PWMx} | $R_{EN} = 10k\Omega$; during T_{INIT} time | | 10 | | uA |
| Power Saving Input (PSI) | | | | | | |
| Power Saving Mode Logic | V _{PSI} | Full-Phase Mode | 1.4 | | | |
| | | Auto-Phase Shedding Mode | 0.8 | | 1.2 | V |
| | | Low-Phase Mode | | | 0.4 | |
| DC Load Line | | | | | | |
| DC Load Line Enable Threshold | | PWM1 resistor strap to GND | 25 | | 200 | kΩ |
| DC Load Line Always Functional | | | 250 | | | kΩ |

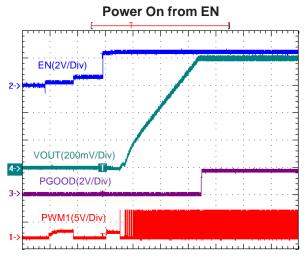


Electrical Characteristics

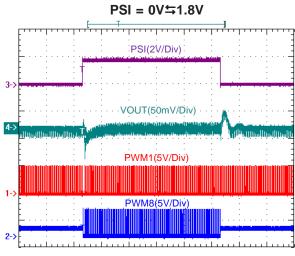
| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|--|-------------------------|---|-----|-----|-----|------|
| IMON | | | | | | |
| IMON Offset Voltage | V _{OF} | $10k\Omega \le R_{IMON} \le 60k\Omega$ | | 0.1 | | V |
| R _{IMON} Range | R _{IMON} | | 10 | | 60 | kΩ |
| Current Mirror Accuracy | | From I _{SUM} to I _{EAP} or I _{MON} | 95 | 100 | 105 | % |
| Protection | | | | | | |
| Channel Current Limit Setting Current | I _{CH_OC} | | | 20 | | uA |
| Total Over Current Protection (OCP) Threshold | V _{OCP} | Measure IMON voltage | | 2.1 | | V |
| Total Over Current Protection (OCP) Delay | T _{OCP} | V _{IMON} > V _{OCP} | | 20 | | us |
| Under Voltage Protection (UVP) Threshold | V _{UVP} | | 40 | 45 | 50 | % |
| Under Voltage Protection (UVP) Delay | T _{UVP} | | | 5 | | us |
| Over Voltage Protection (OVP) Threshold | V _{OVP} | V _{FB} /V _{REFIN} | 150 | 155 | 160 | % |
| Over Voltage Protection (OVP) Delay | T _{OVP} | | | 5 | | us |
| Over Temperature Protection (OTP) Threshold | T _{OTP} | Guaranteed by design | | 160 | | °C |
| Power Good Indicator | | | | | | |
| PGOOD Output Low Level | V _{PG} | I _{SINK} = 4mA | | | 0.3 | V |
| PGOOD Leakage Current | I PG_Leak | V _{PGOOD} = 5V | | | 0.1 | uA |
| SMBus Interface (SCL & SDA) | | | • | | | |
| Input Low Voltage | V _{IL_SMBus} | Guaranteed by design | | | 0.4 | V |
| Input High Voltage | V _{IH_SMBus} | Guaranteed by design | 1.6 | | | V |
| Pull Down Resistance | R _{PULL_SMBus} | Guaranteed by design | | 8 | | Ω |
| Thermal Monitoring (TSENSE) | | , | | • | • | • |
| Source Current | L | | | 120 | | uA |
| Thermal Shutdown Threshold | | PTC type application | | 1.2 | | V |



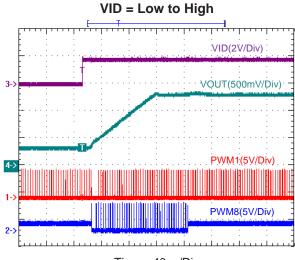
Typical Operation Characteristics



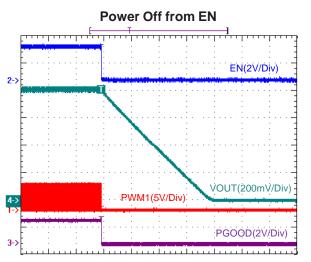
 $\label{eq:time_variance} \begin{aligned} & \text{Time : 200us/Div} \\ & \text{V}_{\text{IN}} = \text{12V, V}_{\text{OUT}} = \text{0.81V, I}_{\text{OUT}} = \text{0A} \end{aligned}$



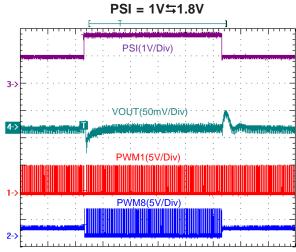
Time : 100us/Div $V_{IN} = 12V$, $V_{OUT} = 0.81V$ (offset), $I_{OUT} = 0A$



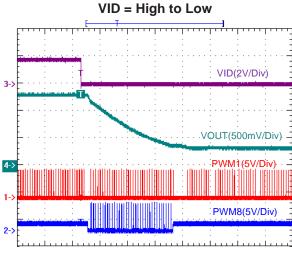
 $\begin{aligned} & \text{Time : 40us/Div} \\ & \text{V}_{\text{IN}} = 12\text{V}, \, \text{V}_{\text{OUT}} = 0.81\text{V}, \, \text{I}_{\text{OUT}} = 0\text{A}, \, \text{C}_{\text{DAC}} = 100\text{nF} \end{aligned}$



 $\begin{aligned} &\text{Time : 200us/Div} \\ &V_{_{IN}} = 12\text{V, V}_{_{OUT}} = 0.81\text{V, I}_{_{OUT}} = 1\text{A} \end{aligned}$



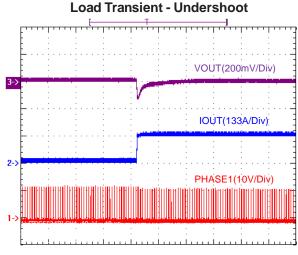
Time : 100us/Div $V_{IN} = 12V$, $V_{OUT} = 0.81V$ (offset), $I_{OUT} = 0A$



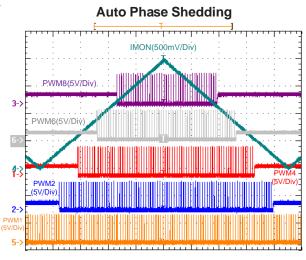
 $\label{eq:vine_power} Time: 40us/Div \\ V_{IN} = 12V, V_{OUT} = 0.81V, I_{OUT} = 0A, C_{DAC} = 100nF$



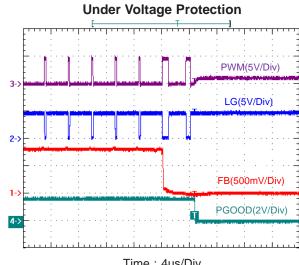
Typical Operation Characteristics



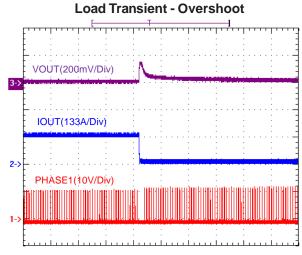
 $\label{eq:Vinequality} \begin{aligned} & \text{Time: 40us/Div} \\ \text{V}_{\text{IN}} = 12\text{V, V}_{\text{OUT}} = 0.81\text{V(offset), I}_{\text{OUT}} = 1\text{A to 150A} \end{aligned}$



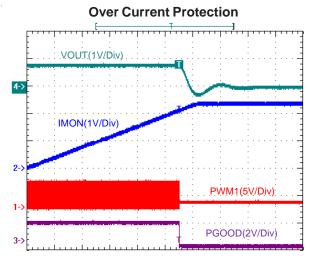
 $\label{eq:time:40us/Div} Time:40us/Div \\ V_{_{IN}}=12V, V_{_{OUT}}=0.81V, V_{_{IMON}}=0V \text{ to } 2V$



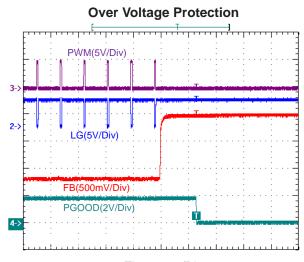
 $\begin{aligned} &\text{Time : 4us/Div} \\ &\text{V}_{\text{IN}} = 12\text{V}, \, \text{V}_{\text{OUT}} = 0.81\text{V}, \, \text{I}_{\text{OUT}} = 0\text{A} \end{aligned}$



 $\label{eq:Vin} \begin{aligned} &\text{Time : 40us/Div} \\ &\text{V}_{\text{IN}} = 12\text{V}, \, \text{V}_{\text{OUT}} = 0.81\text{V} (\text{offset}), \, \text{I}_{\text{OUT}} = 1\text{A to 150A} \end{aligned}$



 $\label{eq:local_control} Time: 200 us/Div \\ V_{IN} = 12 V, V_{OUT} = 0.81 V, V_{IMON} = 0 V to 2.4 V$

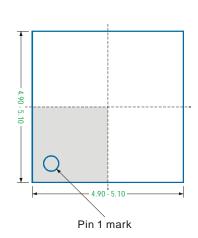


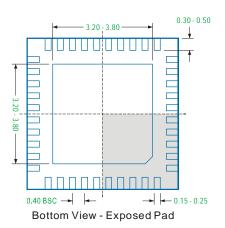
 $\label{eq:local_continuity} \begin{aligned} & \text{Time : 4us/Div} \\ & \text{V}_{\text{IN}} = 12\text{V}, \, \text{V}_{\text{OUT}} = 0.81\text{V}, \, \text{I}_{\text{OUT}} = 0\text{A} \end{aligned}$



Package Information

VQFN5x5 - 40L







Note

1. Package Outline Unit Description:

BSC: Basic. Represents theoretical exact dimension or dimension target

MIN: Minimum dimension specified. MAX: Maximum dimension specified.

REF: Reference. Represents dimension for reference use only. This value is not a device specification.

TYP. Typical. Provided as a general value. This value is not a device specification.

2. Dimensions in Millimeters.

3. Drawing not to scale.

4. These dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm.



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